

Title (en)
METHOD FOR PRODUCING AN ANISOTROPIC CONDUCTIVE FILM

Title (de)
VERFAHREN ZUR HERSTELLUNG EINES ANISOTROP LEITENDES FILMS

Title (fr)
PROCEDE DE FABRICATION DE FILM CONDUCTEUR ANISOTROPE

Publication
EP 1647053 A2 20060419 (FR)

Application
EP 04767896 A 20040715

Priority
• FR 2004050335 W 20040715
• FR 0350352 A 20030718

Abstract (en)
[origin: FR2857780A1] The manufacture of an anisotropic conductor film, called a perforated layer, incorporating a layer of insulating material and some traversing inserts, consists of formation on a substrate with traversing holes; filling the traversing holes to form inserts; the production of a mask covering a first end of the inserts and the engraving of the non-masked part of the end of the inserts to produce pointed ends for the inserts. The manufacture of an anisotropic conductor film, called a perforated layer, incorporating a layer of electrical insulating material and some traversing inserts, consists of: (a) formation on a substrate of at least one layer of material with traversing holes; (b) filling the traversing holes to form the inserts; and (c) production of a mask partially covering a first end of the inserts and the engraving of the non-masked part of the end of the inserts to produce pointed ends for the inserts. Independent claims are also included for the following: (a) the fabrication of a semiconductor chip including the formation of the anisotropic conductor film on a semiconductor slice; and (b) a semiconductor chip fabricated by this method.

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H01L 21/60

IPC 8 full level
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Citation (search report)
See references of WO 2005010926A2

Citation (examination)
• JP S57207362 A 19821220 - MITSUBISHI ELECTRIC CORP
• JP H07320543 A 19951208 - WHITAKER CORP

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